
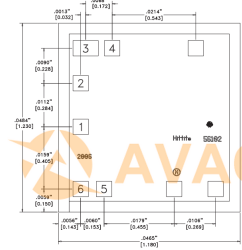


Active RF Multipliers x2 24GHz to 33GHz-OUT 6-Pin Die Tray

Manufacturer:	Analog Devices, Inc
Package/Case:	ic
Product Type:	RF Integrated Circuits
RoHS:	RoHS Compliant/Lead free 
Lifecycle:	Active



Die Packaging Information [1]

Dimension	Alternate [2]
GP-2 (Pin Pad)	

[1] Refer to the "Packaging Information" section for die packaging dimensions.
 [2] Reference this suffix only when ordering alternate die packaging.

NOTES:
 1. ALL DIMENSIONS ARE IN INCHES (MILLIMETERS).
 2. DIE THICKNESS IS .004".
 3. TYPICAL BOND PAD IS .004" SQUARE.
 4. TYPICAL BOND SPACING IS .004" CENTER TO CENTER.
 5. BOND PAD METALLIZATION COLOR.
 6. BACKSIDE METALLIZATION COLOR.
 7. BACKSIDE METAL IS SPINON.
 8. NO CONNECTION REQUIRED FOR UNLABELED BOND PADS.

Images are for reference only

Inquiry

General Description

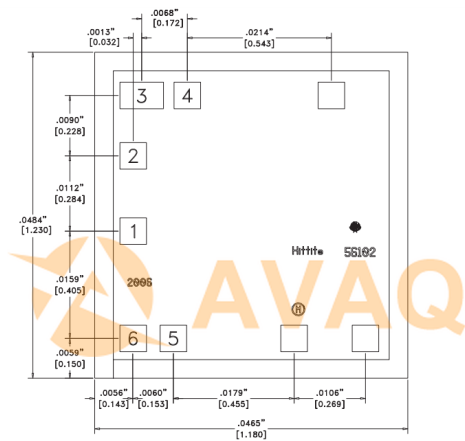
The HMC578 die is a x2 active broadband frequency multiplier utilizing GaAs PHEMT technology. When driven by a +3 dBm signal, the multiplier provides +17 dBm typical output power from 24 to 33 GHz. The Fo and 3Fo isolations are >25 dBc and >36 dBc respectively at 28 GHz. The HMC578 is ideal for use in LO multiplier chains for Pt to Pt & VSAT Radios yielding reduced parts count vs. traditional approaches. The low additive SSB Phase Noise of -132 dBc/Hz at 100 kHz offset helps maintain good system noise performance.

Key Features

- High Output Power: +17 dBm
- Low Input Power Drive: 0 to +6 dBm
- Fo Isolation: >25 dBc @>
- 100 kHz SSB Phase Noise: -132 dBc/Hz
- Single Supply: +5V @ 81 mA
- Die Size: 1.18 x 1.23 x 0.1 mm

Application

- Clock Generation Applications:SONET OC-192 & SDH STM-64
- Point-to-Point & VSAT Radios
- Test Instrumentation
- Military EW / Radar
- Space

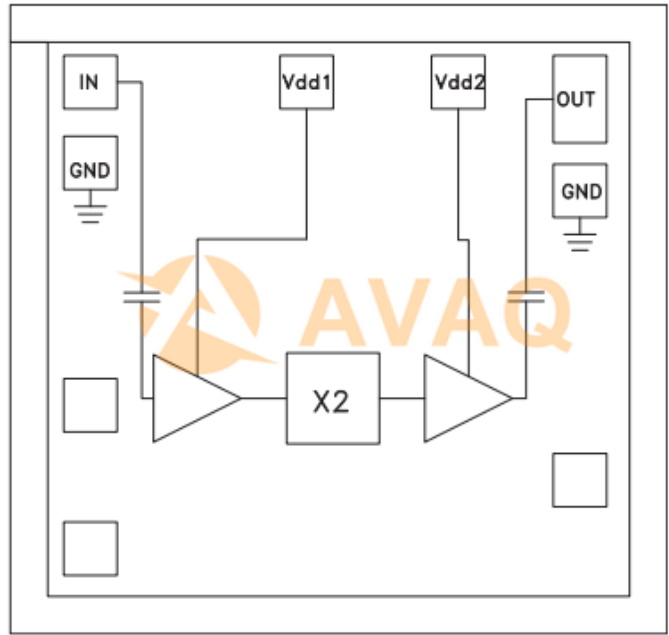


Die Packaging Information ^[1]

Standard	Alternate ^[2]
GP-2 (Gel Pack)	—

[1] Refer to the "Packaging Information" section for die packaging dimensions.
 [2] Reference this suffix only when ordering alternate die packaging.

- NOTES:
1. ALL DIMENSIONS ARE IN INCHES (MILLIMETERS);
 2. DIE THICKNESS IS .004"
 3. TYPICAL BOND PAD IS .004" SQUARE.
 4. TYPICAL BOND SPACING IS .006" CENTER TO CENTER.
 5. BOND PAD METALIZATION: GOLD
 6. BACKSIDE METALIZATION: GOLD
 7. BACKSIDE METAL IS GROUND.
 8. NO CONNECTION REQUIRED FOR UNLABELED BOND PADS.



Recommended For You

HMC624ALP4E

Analog Devices, Inc
 QFN24

HMC952ALP5GE

Analog Devices, Inc
 QFN

HMC361S8GE

Analog Devices, Inc
 SOP-8

HMC253AQS24E

Analog Devices, Inc
 QFN

HMC346MS8G

Analog Devices, Inc
 MSOP8

HMC1119LP4ME

Analog Devices, Inc
 QFN

HMC659LC5

Analog Devices, Inc
 QFN

HMC909LP4E

Analog Devices, Inc
 QFN

HMC564LC4

Analog Devices, Inc
 QFN

HMC1021LP4E

Analog Devices, Inc
 QFN

HMC241AQS16E

Analog Devices, Inc
 SSOP16

HMC424LP3E

Analog Devices, Inc
 QFN

HMC662LP3E

Analog Devices, Inc
 QFN

HMC8038LP4CE

Analog Devices, Inc
 QFN16

HMC363S8G

Analog Devices, Inc
 SOP8